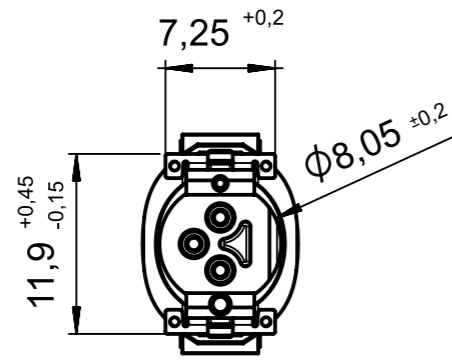
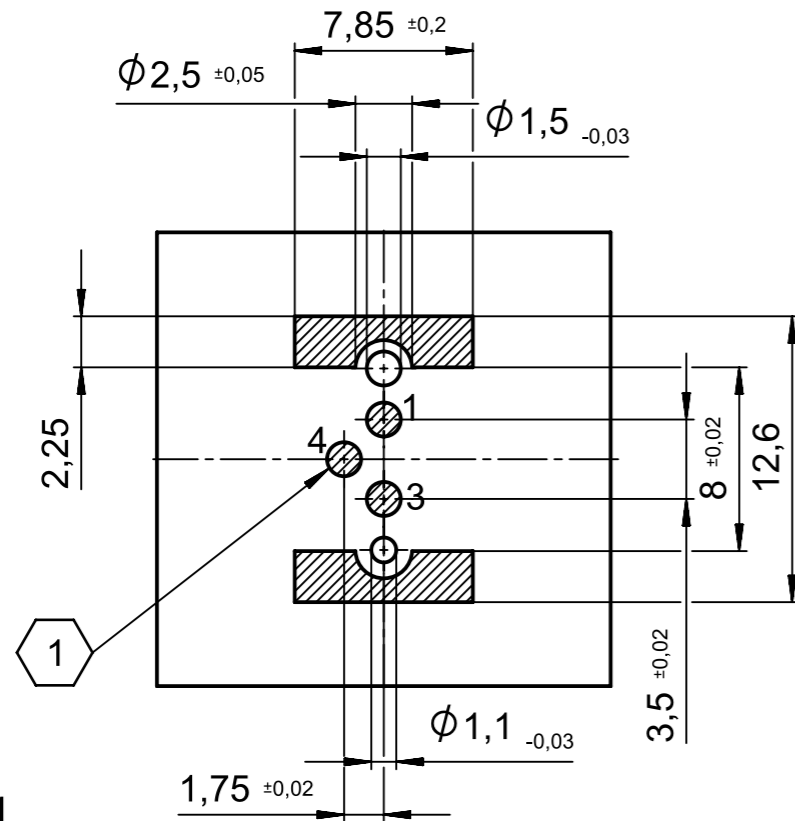


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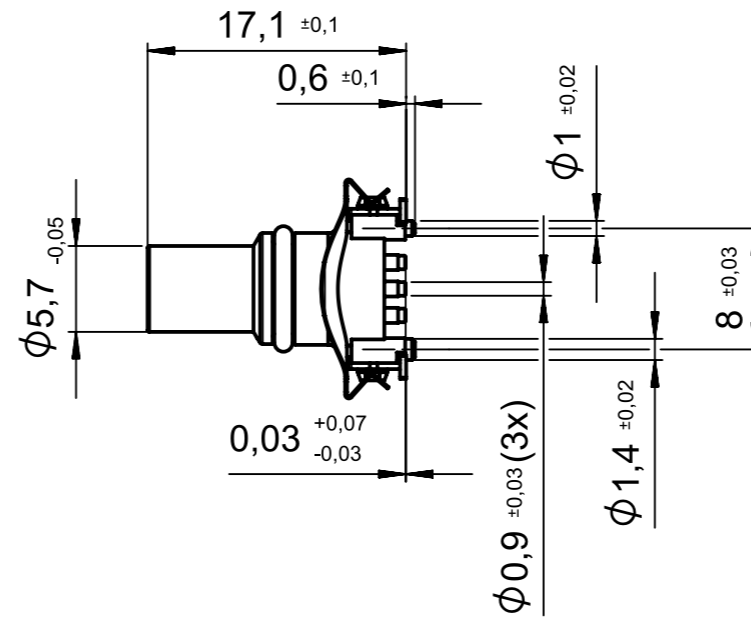
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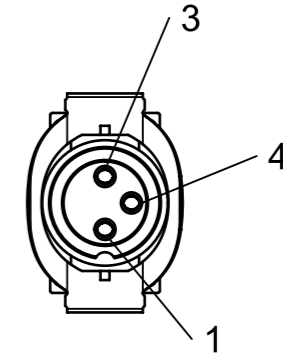
PCB-layout
(advice)



3:1



socket face female



Coplanarity of all contacts and anchor plate \square 0.1

Recommended solder paste thickness 150µm

1 Further information on soldering process and recommended layout, see brochure "Connectors for SMT production"

- EN ISO 291 23/50

	document-no. / ri	article-no. / ri	scale	- Simplified representation - Linear dimensions (mm)
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description				
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